

Appl. No. 10/711,795  
Amdt. dated February 22, 2006  
Reply to Office action of January 10, 2006

**Amendments to the Drawings:**

One replacement sheet of drawings is submitted, having figure 5 thereon. The replacement sheet shows a perspective view of the pseudo-traces of the pseudo-layout 46. Accordingly, the pseudo-layout 46 is no longer cross-hatched. Acceptance of the  
5 corrected drawings is respectfully requested.

Attachment: Replacement Sheet

1 page

Appl. No. 10/711,795  
Amdt. dated February 22, 2006  
Reply to Office action of January 10, 2006

### **REMARKS/ARGUMENTS**

#### **1. Rejection of claims 1-5 under 35 USC 102(e):**

Claims 1-5 are rejected under 35 USC 102(e) as being anticipated by Lin (US 6,534,852)

5

#### **Response:**

Claim 1 has been amended to overcome this rejection. Claim 1 now recites that the PCB is a multi-layered PCB containing a plurality of layers, the circuit layout being formed on at least one layer of the PCB.

10

On the other hand, Lin's disclosure is related to BGA packaging, and does not teach the use of a multi-layered PCB. One skilled in the art would not look to the field of BGA packaging for ideas in avoiding bending in a multi-layer PCB since the two arts do not undergo the same manufacturing processes. Moreover, Lin does not teach that the metal reinforced layer 306 prevents bending in the BGA packaging. Since Lin does not teach all of the limitations contained in the amended claim 1, claim 1 is patentably distinct from Lin. Claims 2-5 are dependent on claim 1, and should be allowed if claim 1 is allowed. Reconsideration of claims 1-5 is respectfully requested.

15

#### **20      2. Rejection of claims 6-7 under 35 USC 103(a):**

Claims 6-7 are rejected under 35 USC 103(a) as being unpatentable over Lin and further in view of Valluri (6,507,100).

#### **Response:**

Valluri's disclosure is related to a chip carrier substrate, and does not teach a multi-layered PCB, as is claimed. Neither Lin nor Valluri teach methods for reducing bending in a multi-layered PCB, and therefore do not teach all of the claim limitations

25

Appl. No. 10/711,795  
Amdt. dated February 22, 2006  
Reply to Office action of January 10, 2006

contained in claim 1.

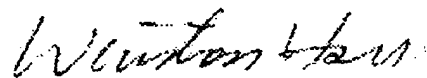
Furthermore, claims 6-7 are dependent on claim 1, and should be allowed if claim 1 is allowed. Reconsideration of claims 6-7 is respectfully requested.

5

In view of the above arguments in favor of patentability, the applicant respectfully requests that a timely Notice of Allowance be issued in this case.

Sincerely yours,

10



Date: 02/22/2006

Winston Hsu, Patent Agent No. 41,526

P.O. BOX 506, Merrifield, VA 22116, U.S.A.

15 Voice Mail: 302-729-1562

Facsimile: 806-498-6673

e-mail : winstonhsu@naipo.com

Note: Please leave a message in my voice mail if you need to talk to me. (The time in D.C.  
20 is 13 hours behind the Taiwan time, i.e. 9 AM in D.C. = 10 PM in Taiwan.)